

## Schottky Rectifier, 3.0 A



SMC



### FEATURES

- 125 °C  $T_J$  operation ( $V_R < 5\text{ V}$ )
- Optimized for OR-ing applications
- Ultra low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Lead (Pb)-free ("PbF" suffix)
- Designed and qualified for industrial level


 Available  
**RoHS\***  
 COMPLIANT

### PRODUCT SUMMARY

$I_{F(AV)}$	3.0 A
$V_R$	15 V
$I_{RM}$	50 mA at 100 °C

### DESCRIPTION

The 30BQ015PbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and very small foot prints on PC boards. The proprietary barrier technology allows for reliable operation up to 125 °C junction temperature. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

### MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	3.0	A
$V_{RRM}$		15	V
$I_{FSM}$	$t_p = 5\ \mu\text{s}$ sine	650	A
$V_F$	1.0 Apk, $T_J = 75\ ^\circ\text{C}$	0.30	V
$T_J$	Range	- 55 to 125	°C

### VOLTAGE RATINGS

PARAMETER	SYMBOL	30BQ015PbF	UNITS
Maximum DC reverse voltage	$V_R$	15	V
Maximum working peak reverse voltage	$V_{RWM}$	25	

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	50 % duty cycle at $T_L = 83\ ^\circ\text{C}$ , rectangular waveform	3.0	A
		50 % duty cycle at $T_L = 78\ ^\circ\text{C}$ , rectangular waveform	4.0	
Maximum peak one cycle non-repetitive surge current	$I_{FSM}$	5 $\mu\text{s}$ sine or 3 $\mu\text{s}$ rect. pulse	650	
		10 ms sine or 6 ms rect. pulse	75	
Non-repetitive avalanche energy	$E_{AS}$	$T_J = 25\ ^\circ\text{C}$ , $I_{AS} = 0.5\ \text{A}$ , $L = 12\ \text{mH}$	1.5	mJ
Repetitive avalanche current	$I_{AR}$	Current decaying linearly to zero in 1 $\mu\text{s}$ Frequency limited by $T_J$ maximum $V_A = 1.5 \times V_R$ typical	0.5	A

\* Pb containing terminations are not RoHS compliant, exemptions may apply



ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	$V_{FM}^{(1)}$	3 A	$T_J = 25\text{ }^\circ\text{C}$	0.35	V
		6 A		0.40	
		3 A	$T_J = 75\text{ }^\circ\text{C}$	0.30	
		6 A		0.35	
Maximum reverse leakage current	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	4	mA
		$T_J = 100\text{ }^\circ\text{C}$		50	
Maximum junction capacitance	$C_T$	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz) 25 °C		1120	pF
Typical series inductance	$L_S$	Measured lead to lead 5 mm from package body		3.0	nH
Maximum voltage rate of change	dV/dt	Rated $V_R$		10 000	V/ $\mu$ s

**Note**

(1) Pulse width < 300  $\mu$ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction temperature range	$T_J^{(1)}$			- 55 to 125	°C
Maximum storage temperature range	$T_{Stg}$			- 55 to 150	
Maximum thermal resistance, junction to lead	$R_{thJL}^{(2)}$	DC operation		12	°C/W
Maximum thermal resistance, junction to ambient	$R_{thJA}$			46	
Approximate weight				0.24	g
				0.008	oz.
Marking device		Case style SMC (similar to DO-214AB)		V3C	

**Notes**

(1)  $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$  thermal runaway condition for a diode on its own heatsink

(2) Mounted 1" square PCB

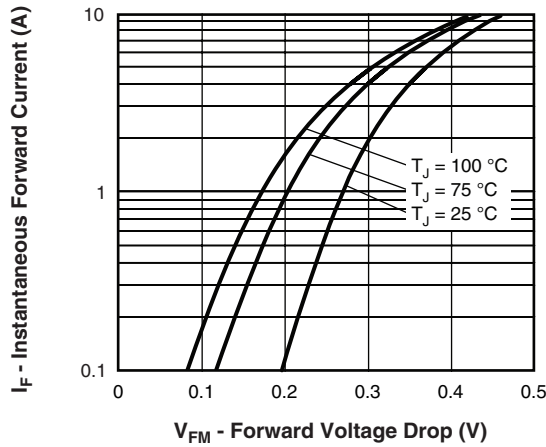


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

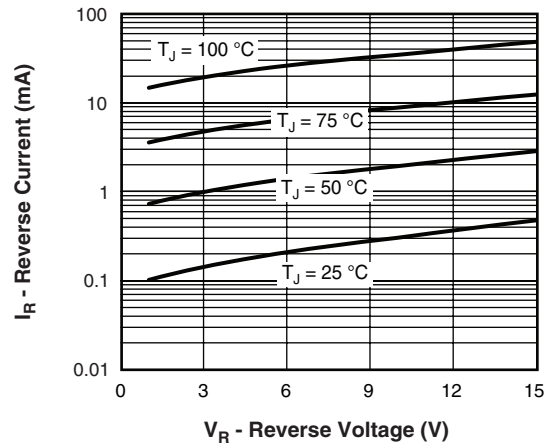


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

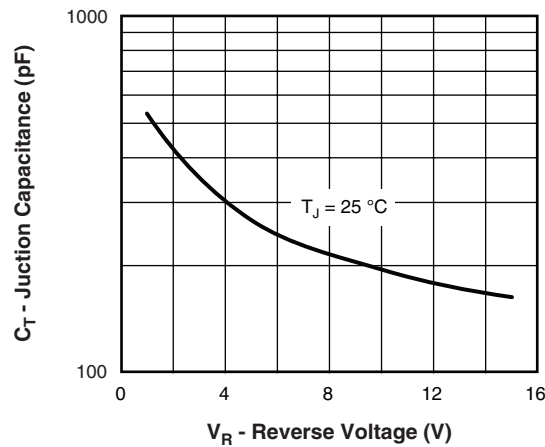


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

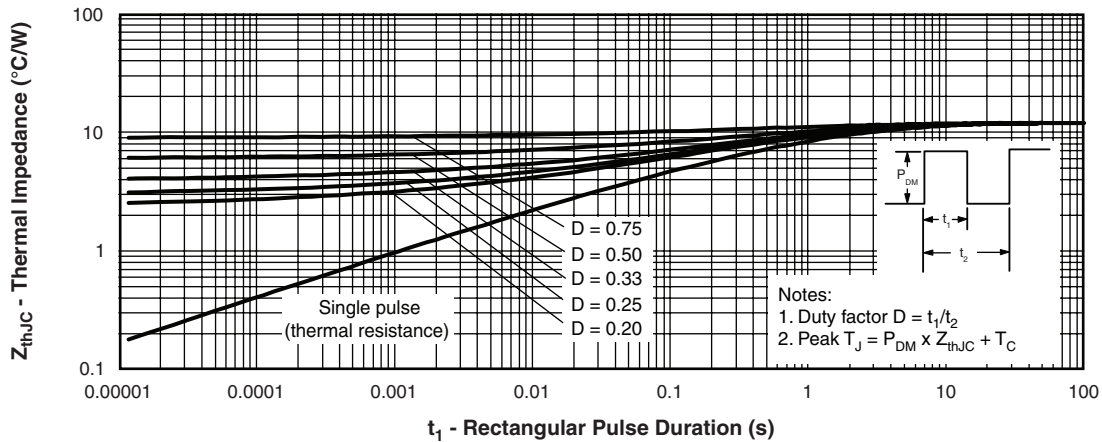


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)

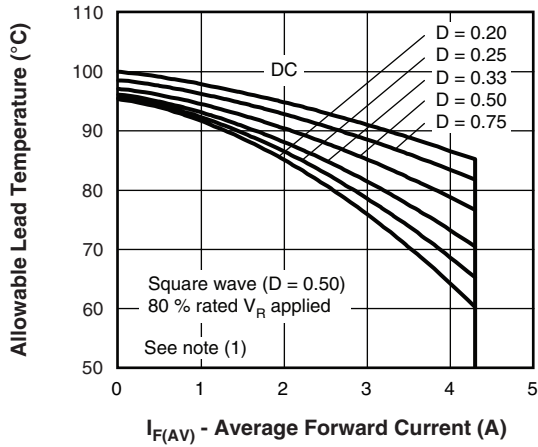


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature

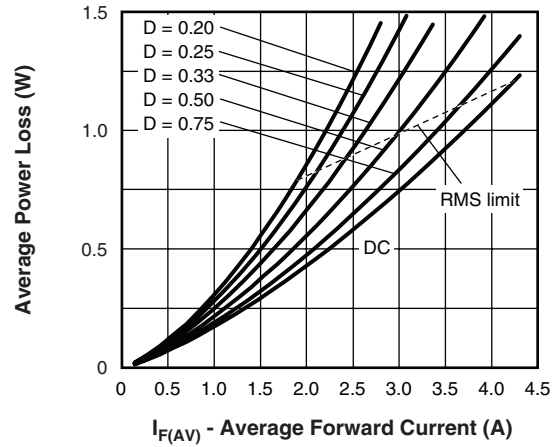


Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

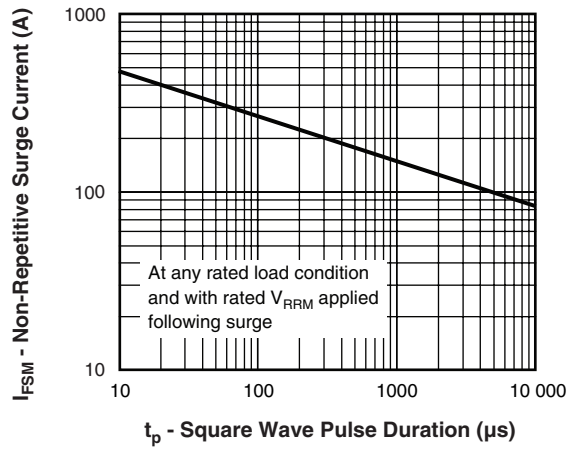


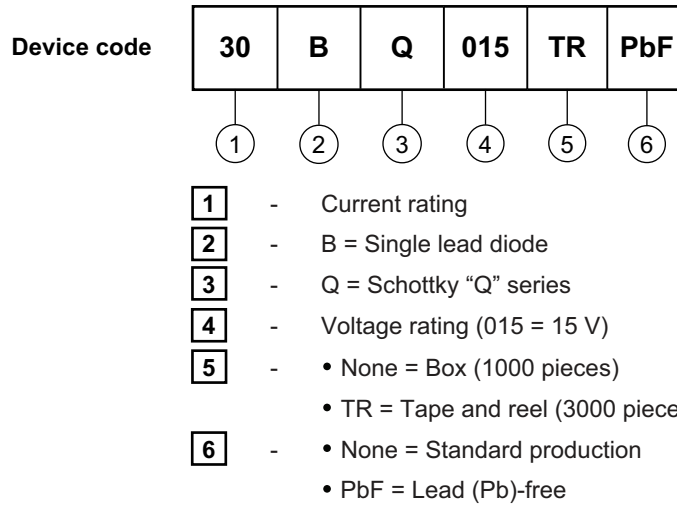
Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

**Note**

- (1) Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;  
 $Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D)$  (see fig. 6);  
 $Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 80\%$  rated  $V_R$



**ORDERING INFORMATION TABLE**



LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95023">http://www.vishay.com/doc?95023</a>
Part marking information	<a href="http://www.vishay.com/doc?95029">http://www.vishay.com/doc?95029</a>
Packaging information	<a href="http://www.vishay.com/doc?95034">http://www.vishay.com/doc?95034</a>



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